# J-15-01

#### S/N Unknown

Title:

# PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kishore K. Chakravorty
Serial No.: Unknown

Examiner: Unknown Group Art Unit: Unknown

Docket: 884.267US1

Filed: Herewith

ELECTRONIC ASSEMBLY COMPRISING INTERPOSER WITH

EMBEDDED CAPACITORS AND METHODS OF MANUFACTURE

10862 U.S. 09/62870

### INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant further request that a copy of the 1449 form, initialed by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Please charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KISHORE K. CHAKRAVORTY

By his Representatives,

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Date July 31, 2000

Ann M. McCrackin Reg. No. 42.858

CERTIFICATE UNDER 37 CFR 1.10.

"Express Mail" mailing label number: EL600376773US

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Thereby certify that this paper or fee is being deposited with the United States Postal Service "Express May Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Shawn Hise

Signature

Name



Form 1449\* Atty. Docket No.: 884.267US1 Serial No. Unknown

INFORMATION DISCLOSURE STATEMENT
BY APPLICANT
(Use several sheets if necessary)

Filing Date: Herewith Group: Unknown

#### U.S. PATENT DOCUMENTS Filing Date C \*\*Examiner Subclass Date C1266 If Appropriate FOREIGN PATENT DOCUMENTS \*\*Examiner Class Subclass Date Initial ument Number Country OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.) \*\*Evanines Initial "Advances in MCM Ceramics", Solid State Technology, Amey, D., et al., 143-146, (1997) Baniecki, J., et al., "Dielectric Relaxation of Ba0.7 Sr0.3 TiO3 Thin Films from 1 mHz to 20 GHz", Appl. Phys. Letter 72(4), 1998 American Institute of Physics, 198-500, (Jan. 1998) "Fabrication and Characterization of Multilayer Capacitors Chan, Y., et al., Buried in a Low Temperature Co-Fired Ceramic Substrate", Active and Passive Elec. Comp. Vol. 20, 215-224, (1998) Choi, K.L., et al., "Characterization of Embedded Passives Using Macromodels in LTCC Technology", IEEE Transactions on Components, Packaging, and Manufacturing Technology, Vol. 21, 258-268, (Aug. 1998) Eurskens, W., et al., "Design and Performance of UHF Band Inductors, Capacitors and Resonators Using LTCC Technology for Mobile Communication Systems", 1998 IEEE MTT-S Digest, 1285-1288, (1998) Koschmieder, T., et al., "Ceramic Substrate Thickness, Test Board Thickness, and Part Spacing: A Screening Doe", Proceedings of SMTA International Conference, 6 pgs., (Sept. 1999) Mistler, R.E., "Tape Casting: Past, Present, Potential", The American Ceramic Society Bulletin, 82-86, (Oct. 1998) Nishimura, T., et al., "3.5 V Operation Driver-Amplifier MMIC Utilizing SrTiO3 Capacitors for 1.95 GHz Wide-Band CDMA Cellular Phones", 1998 IEEE MTT-S Digest, 447-450, (1998) Rector, Jr., J., et al., "Integrated and Integral Passive Components: A Technology Roadmap", 1997 Electronic Components and Technology Conference, 713-723, (1997)

Examiner	Date	Considered
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\*Substitute Disclosure Statement Form (PTO-1449)

\*\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609, Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Sheet 2 of 2

Form 1449\* Atty. Docket No.: 884.267US1 Serial No. Unknown INFORMATION DISCLOSURE STATEMENT Applicant: Kishore K. Chakravorty BY APPLICANT Filing Date: Herewith Group: Unknown (Use several sheets if necessary)

OTHER DOCUMENTS
(Including Author, Title, Date, Pertinent Pages, Etc.) \*\*Examiner Initial

Scrantom, S., et al., "Manufacture of Embedded Integrated Passive Components Into Low Temperature Co-Fired Ceramic Systems", <u>1938 International Symposium</u> on Microelectronics, 459-466, (1998)
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Tok, A.I., et al., "Tape Casting of Composite Ceramic Substrates Using Hollow Micro-Speherical Powders", <u>Processing and Pabrication of Advanced Materials YII</u> , <u>Proceedings of a Symposium organized by:</u> The Minerals, Metals & Materials Society (TMS), Warrendale, PA, USA, 451-461, (Oct. 1998)
Ueda, T., et al., "GaAs MMIC Chip-sets for Mobile Communication Systems with On-chip Ferroelectric Capacitors", <u>Integrated Ferroelectrics</u> , <u>Vol. 7</u> , 45-60, (1995)
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